

74AHC1G09-Q100

2-input AND gate with open-drain output

Rev. 2 — 16 August 2012

Product data sheet

1. General description

The 74AHC1G09-Q100 is a high-speed Si-gate CMOS device.

The 74AHC1G09-Q100 provides the 2-input AND function with open-drain output.

The output of the 74AHC1G09-Q100 is an open drain and can be connected to other open-drain outputs to implement active-LOW, wired-OR or active-HIGH wired-AND functions. For digital operation, this device must have a pull-up resistor to establish a logic HIGH level.

This product has been qualified to the Automotive Electronics Council (AEC) standard Q100 (Grade 1) and is suitable for use in automotive applications.

2. Features and benefits

- Automotive product qualification in accordance with AEC-Q100 (Grade 1)
 - ◆ Specified from -40°C to $+85^{\circ}\text{C}$ and from -40°C to $+125^{\circ}\text{C}$
- High noise immunity
- Low power dissipation
- SOT353-1 and SOT753 package options
- ESD protection:
 - ◆ MIL-STD-883, method 3015 exceeds 2000 V
 - ◆ HBM JESD22-A114F exceeds 2000 V
 - ◆ MM JESD22-A115-A exceeds 200 V ($C = 200\text{ pF}$, $R = 0\ \Omega$)

3. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
74AHC1G09GW-Q100	-40°C to $+125^{\circ}\text{C}$	TSSOP5	plastic thin shrink small outline package; 5 leads; body width 1.25 mm	SOT353-1
74AHC1G09GV-Q100	-40°C to $+125^{\circ}\text{C}$	SC-74A	plastic surface-mounted package; 5 leads	SOT753



4. Marking

Table 2. Marking

Type number	Marking code
74AHC1G09GW-Q100	A9
74AHC1G09GV-Q100	A09

5. Functional diagram

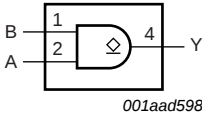


Fig 1. Logic symbol

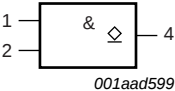


Fig 2. IEC logic symbol

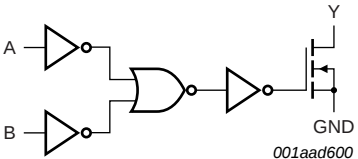


Fig 3. Logic diagram

6. Pinning information

6.1 Pinning

74AHC1G09-Q100

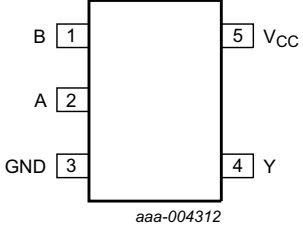


Fig 4. Pin configuration SOT353-1 (TSSOP5) and SOT753 (SC-74A)

6.2 Pin description

Table 3. Pin description

Symbol	Pin	Description
B	1	data input B
A	2	data input A
GND	3	ground (0 V)
Y	4	data output Y
V _{CC}	5	supply voltage

7. Functional description

Table 4. Function table^[1]

Input		Output
A	B	Y
L	L	L
L	H	L
H	L	L
H	H	Z

[1] H = HIGH voltage level; L = LOW voltage level; Z = high-impedance OFF-state.

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CC}	supply voltage		-0.5	+7.0	V
V _I	input voltage		^[1] -0.5	+7.0	V
V _O	output voltage	active mode	^[1] -0.5	+7.0	V
		high-impedance mode	^[1] -0.5	+7.0	V
I _{IK}	input clamping current	V _I < -0.5 V	^[1] -	-20	mA
I _{OK}	output clamping current	V _O < -0.5 V	^[1] -	±20	mA
I _O	output current	V _O > -0.5 V	-	25	mA
I _{CC}	supply current		-	±75	mA
I _{GND}	ground current		-	±75	mA
T _{stg}	storage temperature		-65	+150	°C
P _{tot}	total power dissipation	T _{amb} = -40 °C to +125 °C	^[2] -	250	mW

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] For TSSOP5 and SC-74A packages: above 87.5 °C the value of P_{tot} derates linearly with 4.0 mW/K.

9. Recommended operating conditions

Table 6. Recommended operating operations

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V _{CC}	supply voltage		2.0	5.0	5.5	V
V _I	input voltage		0	-	5.5	V
V _O	output voltage	active mode	0	-	V _{CC}	V
		high-impedance mode	0	-	6.0	V
T _{amb}	ambient temperature		-40	+25	+125	°C
Δt/ΔV	input transition rise and fall rate	V _{CC} = 3.0 V to 3.6 V	-	-	100	ns/V
		V _{CC} = 4.5 V to 5.5 V	-	-	20	ns/V

10. Static characteristics

Table 7. Static characteristics

Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	25 °C			–40 °C to +85 °C		–40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
V _{IH}	HIGH-level input voltage	V _{CC} = 2.0 V	1.5	-	-	1.5	-	1.5	-	V
		V _{CC} = 3.0 V	2.1	-	-	2.1	-	2.1	-	V
		V _{CC} = 5.5 V	3.85	-	-	3.85	-	3.85	-	V
V _{IL}	LOW-level input voltage	V _{CC} = 2.0 V	-	-	0.5	-	0.5	-	0.5	V
		V _{CC} = 3.0 V	-	-	0.9	-	0.9	-	0.9	V
		V _{CC} = 5.5 V	-	-	1.65	-	1.65	-	1.65	V
V _{OL}	LOW-level output voltage	V _I = V _{IH} or V _{IL}								
		I _O = 50 µA; V _{CC} = 2.0 V	-	0	0.1	-	0.1	-	0.1	V
		I _O = 50 µA; V _{CC} = 3.0 V	-	0	0.1	-	0.1	-	0.1	V
		I _O = 50 µA; V _{CC} = 4.5 V	-	0	0.1	-	0.1	-	0.1	V
		I _O = 4.0 mA; V _{CC} = 3.0 V	-	-	0.36	-	0.44	-	0.55	V
		I _O = 8.0 mA; V _{CC} = 4.5 V	-	-	0.36	-	0.44	-	0.55	V
I _I	input leakage current	V _I = 5.5 V or GND; V _{CC} = 0 V to 5.5 V	-	-	±0.1	-	±1.0	-	±2.0	µA
I _{OZ}	OFF-state output current	V _I = V _{IH} or V _{IL} ; V _O = V _{CC} or GND; V _{CC} = 5.5 V	-	-	±0.25		±2.5		±10.0	µA
I _{CC}	supply current	V _I = V _{CC} or GND; I _O = 0 A; V _{CC} = 5.5 V	-	-	1.0	-	10	-	20	µA
C _I	input capacitance		-	1.5	10	-	10	-	10	pF

11. Dynamic characteristics

Table 8. Dynamic characteristics

GND = 0 V; for test circuit see [Figure 6](#).

Symbol	Parameter	Conditions	25 °C			–40 °C to +85 °C		–40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
t _{pd}	propagation delay	A and B to Y; see Figure 5								
		V _{CC} = 3.0 V to 3.6 V								
		C _L = 15 pF	-	4.6	7.5	1.0	8.5	1.0	9.0	ns
		C _L = 50 pF	-	6.5	11.0	1.5	12.0	1.5	12.5	ns
		V _{CC} = 4.5 V to 5.5 V								
		C _L = 15 pF	-	3.2	5.5	1.0	6.5	1.0	7.0	ns
		C _L = 50 pF	-	4.6	7.5	1.5	8.0	1.5	8.5	ns
C _{PD}	power dissipation capacitance	C _L = 50 pF; f _i = 1 MHz; V _I = GND to V _{CC}	-	5	-	-	-	-	-	pF

[1] t_{pd} is the same as t_{pZL} and t_{pLZ}.

[2] Typical values are measured at V_{CC} = 3.3 V.

- [3] Typical values are measured at $V_{CC} = 5.0\text{ V}$.
- [4] C_{PD} is used to determine the dynamic power dissipation (P_D in μW).
- $P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + (C_L \times V_{CC}^2 \times f_o)$ where:
- f_i = input frequency in MHz;
 - f_o = output frequency in MHz;
 - C_L = output load capacitance in pF;
 - V_{CC} = supply voltage in V;
 - N = number of inputs switching;
 - $(C_L \times V_{CC}^2 \times f_o)$ = dissipation due to the output if the combination of the pull-up voltage and resistance results in V_{CC} at the output.

12. Waveforms

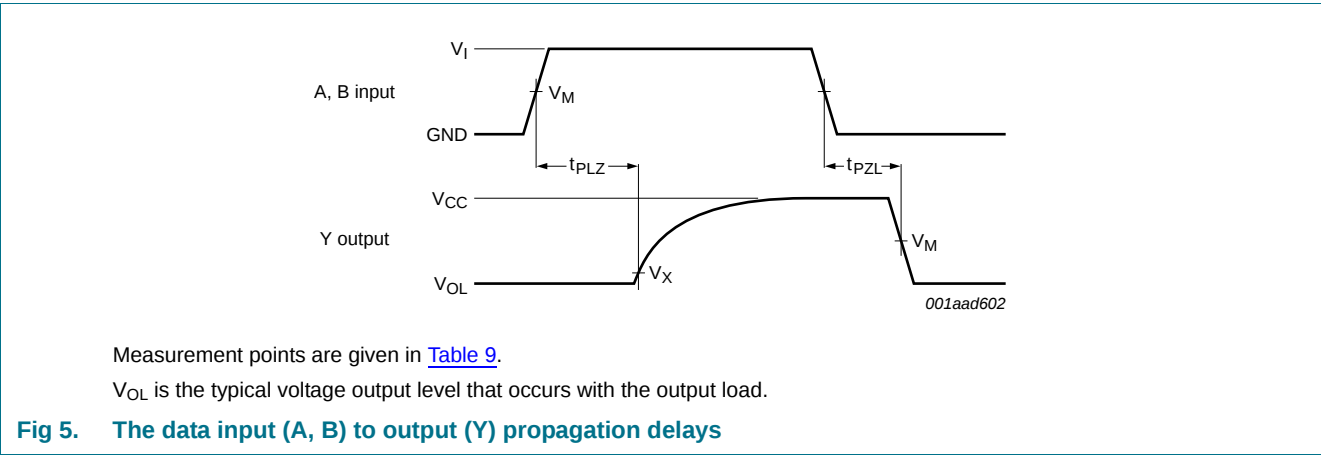


Table 9. Measurement points

Input	Output	
V_M	V_M	V_X
$0.5V_{CC}$	$0.5V_{CC}$	$V_{OL} + 0.3\text{ V}$

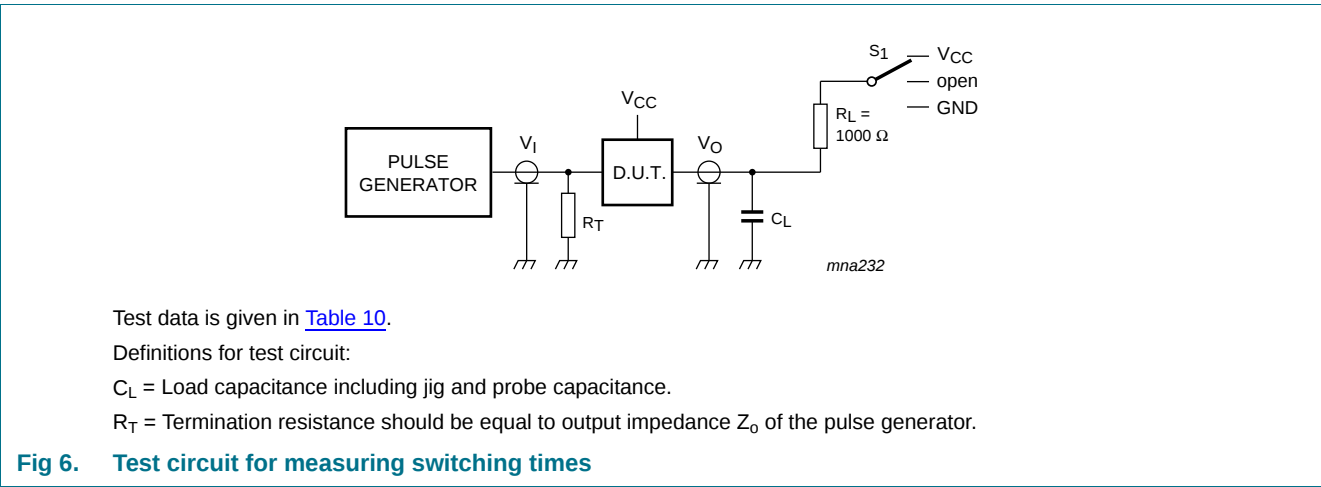


Table 10. Test data

Input		Load		S ₁		
V _I	t _r , t _f	R _L	C _L	t _{PHZ} , t _{PZH}	t _{PLZ} , t _{PZL}	t _{PLH} , t _{PHL}
GND to V _{CC}	≤ 3.0 ns	1000 Ω	15 pF	GND	V _{CC}	open
GND to V _{CC}	≤ 3.0 ns	1000 Ω	50 pF	GND	V _{CC}	open

13. Package outline

TSSOP5: plastic thin shrink small outline package; 5 leads; body width 1.25 mm

SOT353-1

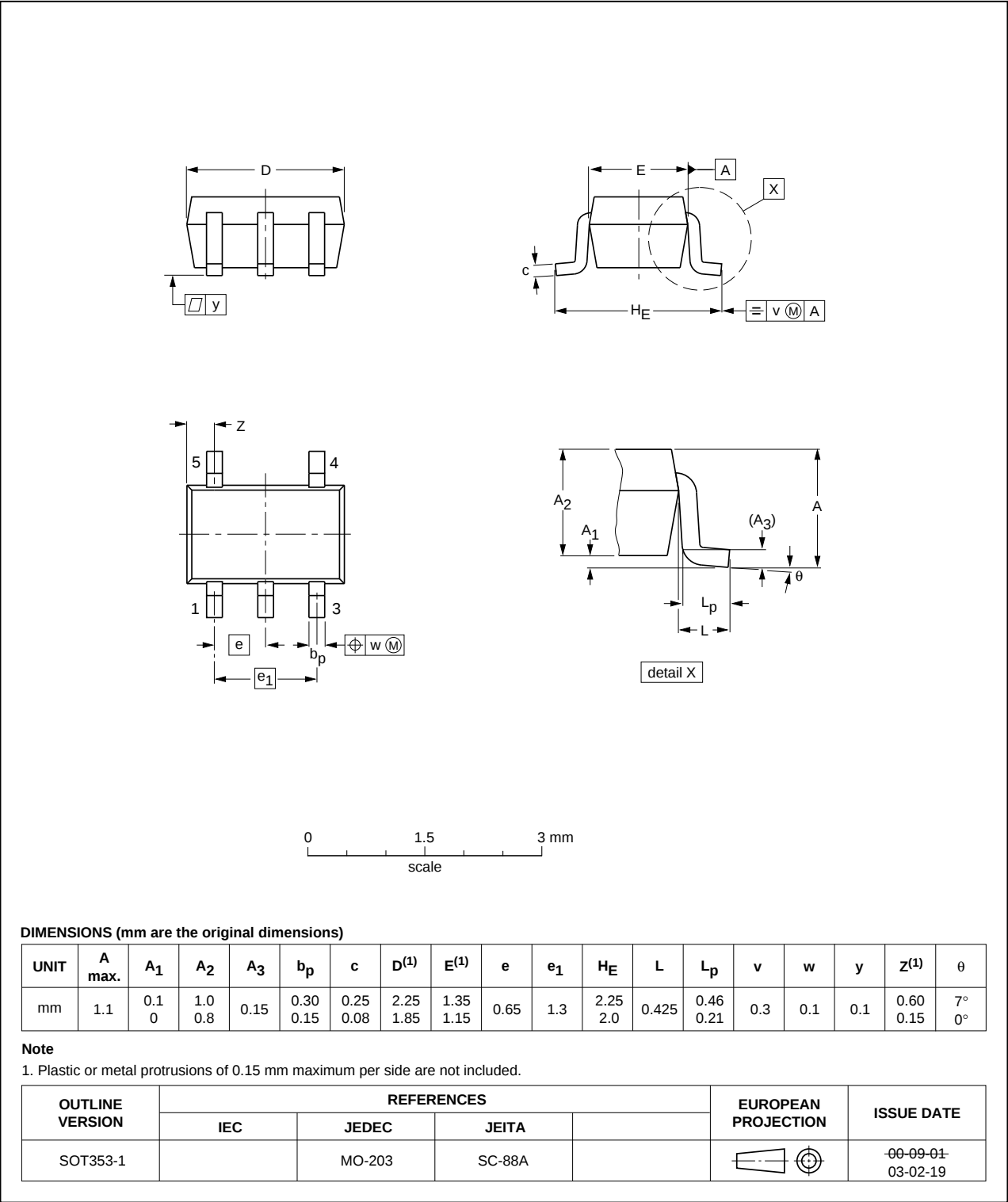


Fig 7. Package outline SOT353-1 (TSSOP5)

Plastic surface-mounted package; 5 leads

SOT753

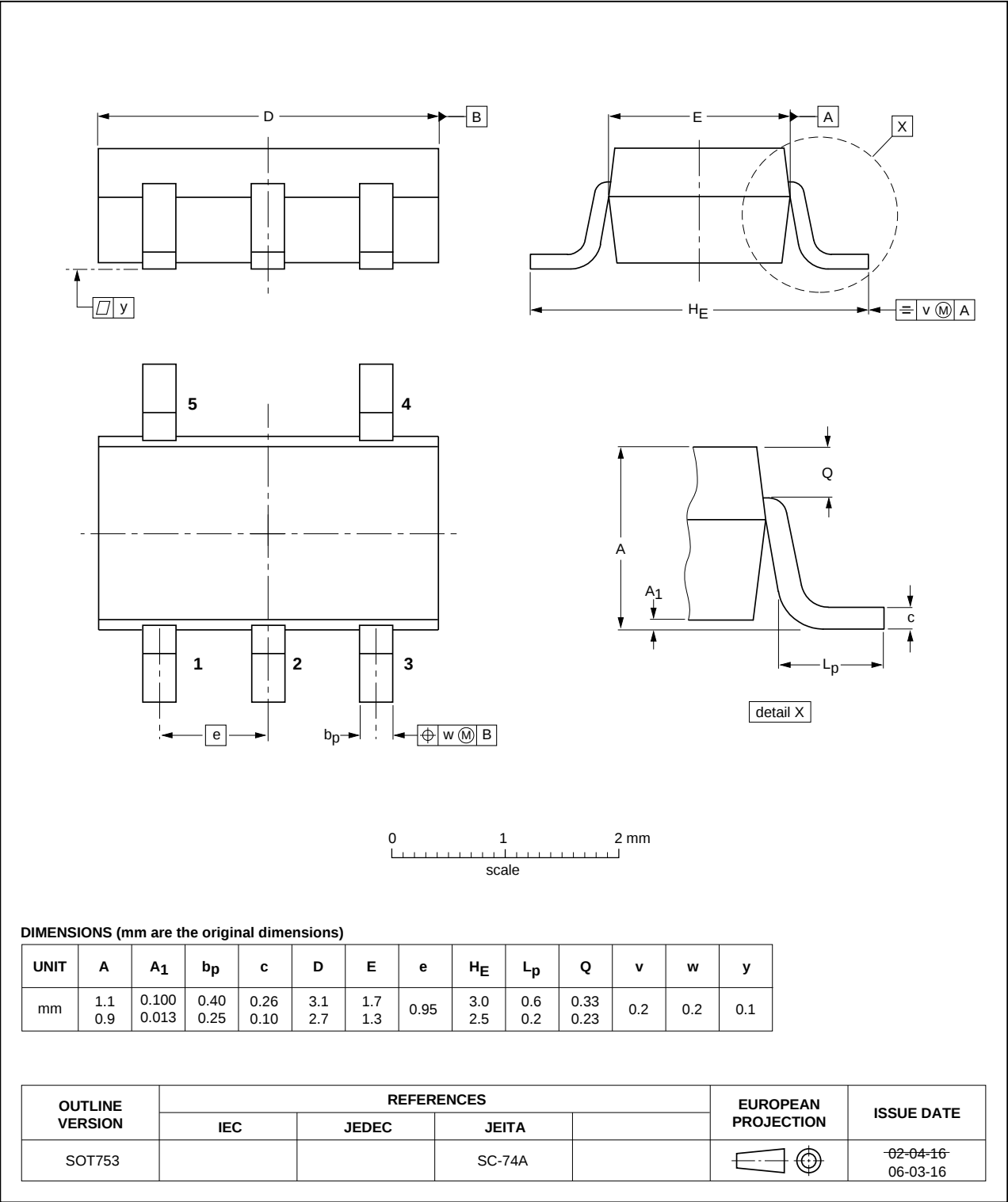


Fig 8. Package outline SOT753 (SC-74A)

14. Abbreviations

Table 11. Abbreviations

Acronym	Description
CDM	Charged Device Model
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model
MIL	Military

15. Revision history

Table 12. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74AHC1G09_Q100 v.2	20120816	Product data sheet	-	74AHC1G09_Q100 v.1
Modifications:	• Features list corrected (errata).			
74AHC1G09_Q100 v.1	20120807	Product data sheet	-	-

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16.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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Product [short] data sheet	Production	This document contains the product specification.

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18. Contents

1	General description	1
2	Features and benefits	1
3	Ordering information	1
4	Marking	2
5	Functional diagram	2
6	Pinning information	2
6.1	Pinning	2
6.2	Pin description	2
7	Functional description	3
8	Limiting values	3
9	Recommended operating conditions	3
10	Static characteristics	4
11	Dynamic characteristics	4
12	Waveforms	5
13	Package outline	7
14	Abbreviations	9
15	Revision history	9
16	Legal information	10
16.1	Data sheet status	10
16.2	Definitions	10
16.3	Disclaimers	10
16.4	Trademarks	11
17	Contact information	11
18	Contents	12

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